

Abstract

**Method for mechanically removing solder beads
on the surface of printed circuit boards**

The invention relates to a method for mechanical-
5 ly removing solder beads (14) from the surface of printed
circuit boards (10) directly after they pass through the
solder flow during flow soldering of printed circuit
boards in a soldering plant. In order to ensure that the
solder beads are mechanically removed without damaging
10 the printed circuit boards, the solder beads 14 are
mechanically removed by means of at least one jet (50) of
cold gas directed onto the surface (Figure 1).

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